

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YE SEUL KIM	01/07/2016
KYOUNG WAN KIM	01/07/2016
YEO JIN YOON	01/07/2016
SANG HYUN OH	01/07/2016
KEUM JU LEE	01/07/2016
JIN WOONG LEE	01/07/2016
DA YEON JEONG	01/08/2016
SANG WON WOO	01/06/2016
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<b>Name:</b>	SEOUL VIOSYS CO., LTD.
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<b>City:</b>	ANSAN-SI
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	425-851
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14984829
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<b>ATTORNEY DOCKET NUMBER:</b>	114896-8036.US02
<b>NAME OF SUBMITTER:</b>	MICHELLE MELENDEZ

PATENT

<b>SIGNATURE:</b>	/Michelle Melendez/
<b>DATE SIGNED:</b>	01/19/2016
	This document serves as an Oath/Declaration (37 CFR 1.63).
<b>Total Attachments: 5</b> source=Executed Declaration and Assignment#page1.tif source=Executed Declaration and Assignment#page2.tif source=Executed Declaration and Assignment#page3.tif source=Executed Declaration and Assignment#page4.tif source=Executed Declaration and Assignment#page5.tif	

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Ye Seul Kim et al.

Application No.: Not Yet Assigned

Conf. No.: Not Yet Assigned

Filed: Herewith

For: LIGHT EMITTING DIODE CHIP HAVING  
ELECTRODE PAD

**DECLARATION AND ASSIGNMENT BY THE INVENTOR**  
**UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012**

As a below named inventor, I hereby declare that:

I believe I am the sole original inventor or an original joint inventor of a claimed invention in a patent application entitled:

**LIGHT EMITTING DIODE CHIP HAVING ELECTRODE PAD**

filed on December 30, 2016, and assigned U.S. Application Number 14/984,829, the specification of which is attached hereto and identified as Attorney Docket No. 114896-8036.US02. I authorize and request an attorney appointed in the above-identified U.S. application to hereafter insert above the filing date and application number of the above-identified U.S. patent application when known.

I believe the following persons are original joint inventors of the above-identified U.S. patent application:

Ye Seul Kim;

Kyoung Wan Kim;

Yeo Jin Yoon;

Sang Hyun Oh;

Keum Ju Lee;

Jin Woong Lee;

Da Yeon Jeong; and

Sang Won Woo.

I made, authorized to make, or will make or authorize to make the above-identified patent application at the U.S. Patent and Trademark Office.

I have reviewed and understand the contents of the above-identified patent application including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

#### ASSIGNMENT

I hereby assign to Seoul Viosys Co., Ltd., a corporation, having a place of business at #1B-36, 65-16, Sandan-ro 163beon-gil, Danwon-gu, Ansan-si, Gyeonggi-do 425-851, Republic of Korea, and its successors and assigns (collectively "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in the above-identified application, and prior U.S. Patent Application No. 14/630,273, filed in the United States Patent Office on February 24, 2015, prior U.S. Patent Application No. 13/885,777, filed in the United States Patent Office on May 16, 2013, issued as U.S. Patent Number 8,987,772 on March 24, 2015, prior PCT Application No. PCT/KR2011/001385, filed in the Republic of Korea Receiving Office on February 28, 2011, prior Korean Patent Application No. 10-2010-0114747 filed in the Republic of Korea on November 18, 2010, prior Korean Patent Application No. 10-2010-0114748 filed in the Republic of Korea on November 18, 2010, and prior Korean Patent Application No. 10-2014-0195165 filed in the Republic of Korea on December 31, 2014, from which the above-identified U.S. patent application claims priorities and benefits.

This assignment includes the entire right, title and interest in the above-identified U.S., PCT and Korean patent applications, all legal equivalents thereof in any country, any and all United States, Patent Cooperation Treaty, Republic of Korea and other foreign patents, utility models, and design registrations granted for any of said inventions and improvements, including, but not limited to, all divisions, continuations, reissues, reexamination certificates, any and all certificates issued in any post-grant proceeding, and extensions of said applications and patents

of the United States, Patent Cooperation Treaty and Republic of Korea, all other foreign patents, utility models, and design registrations, and the right to claim priority based on the filing dates of the above-identified U.S. and Republic of Korea patent applications under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes, and the right to seek relief and recover all damages, including, but not limited to, a reasonable royalty, by reason of infringement or any other violation of patent or patent application rights. I authorize the Assignee to apply in all countries in the name of the Assignee for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements.

In addition, I hereby confirm the sale, assignment, and transfer to the Assignee of the entire right, title and interest throughout the world in said inventions and improvements that occurred by operation of an employment agreement between me and the Assignee existing at the time said inventions and improvements were made. Should I have any remaining interest, I hereby sell, assign, and transfer any right, title and interest I may have in said inventions and improvements anywhere in the world to the Assignee.

The foregoing assignments, sale and transfer have been made for good and valuable consideration in accordance with the aforementioned employment agreement.

I hereby represent and covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with the assignment of said inventions and improvements to the Assignee.

I further covenant for myself and my respective heirs, legal representatives and assigns, to assist the Assignee in handling various procedures, tasks and documentation in connection with this assignment, including, but not limited to, providing to the Assignee promptly upon the request of the Assignee all pertinent facts and documents relating to said invention and improvements, and said patents, said legal equivalents or other legal instrument as may be known and accessible to me and testifying as to the same in any interference, litigation, or proceeding relating thereto, and promptly executing and delivering to the Assignee or its legal representative any and all papers, documents, instruments or affidavits in connection with obtaining, maintaining, issuing or enforcing said application, said inventions and improvements,

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and said patents, said equivalents and other legal instrument which may be necessary or desirable to carry out the purposes thereof.

I hereby authorize and request the Commissioner of Patents and Trademarks to issue one or more patents in the United States for said inventions and improvements to Seoul Viosys Co., Ltd. as assignee of the entire interest, for the sole use and benefit of Assignee, its successors and assigns.

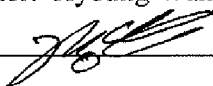
I am competent to execute the above declaration and assignment. I hereby have duly executed the declaration and assignment below with my name.

Full name of first inventor: Ye Seul Kim

Inventor's signature: 

Date: 2016. 1. 7.

Full name of joint inventor: Kyoung Wan Kim

Inventor's signature: 

Date: 2016. 1. 7.

Full name of joint inventor: Yeo Jin Yoon

Inventor's signature: 

Date: 2016. 1. 7.

Full name of joint inventor: Sang Hyun Oh

Inventor's signature: 

Date: 2016. 1. 7.

Full name of joint inventor: Keum Ju Lee

Inventor's signature: 

Date: 2016. 1. 7.

Full name of joint inventor: Jin Woong Lee

Inventors : Ye Seul Kim et al.  
Appl. No. : Not Yet Assigned  
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Page : 5 of 5

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Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Full name of joint inventor: Da Yeon Jeong

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Full name of joint inventor: Sang Won Woo

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

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